

TGL2207–SM 2.0 – 6.5 GHz 100 Watt VPIN Limiter

Product Overview

The Qorvo TGL2207-SM is a high power, wideband GaAs VPIN limiter capable of protecting sensitive receive channel components against high power incident signals. The TGL2207-SM does not require DC bias and achieves a low insertion loss all in a small form factor. These features allow for simple integration with minimal impact to system performance.

The TGL2207-SM operates from 2.0 to 6.5 GHz with low insertion loss of less than 1.0 dB. It can limit up to 100 W incident pulsed-power with a low flat leakage of less than 15.5 dBm.

The TGL2207-SM is offered in a 5 x 5 mm air-cavity QFN packaged limiter comprised of a ceramic base with a plastic epoxy-sealed lid. It is well suited for both commercial and defense related applications.

Lead-free and RoHS compliant.

TriQuint TGL 2207-SM

32 Pad 5 x 5 mm QFN Package

Key Features

• Frequency Range: 2.0 to 6.5 GHz

• Insertion Loss: < 1.0 dB

Peak Power Handling: 100 W (pulsed)

Flat Leakage: < 15.5 dBmSpike Leakage < 16.0 dBm

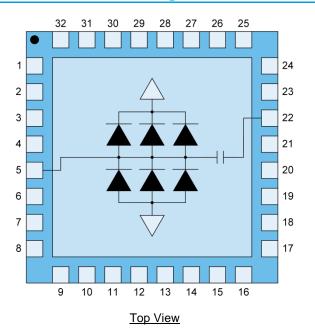
• Recovery Time: < 115 ns

Passive (no DC bias required)

Integrated DC Block on output

Package Dimensions: 5.00 x 5.00 x 1.45 mm

Functional Block Diagram



Applications

- Receive Chain Protection
- Commercial and Military Radar

Ordering Information

| Part | Description | |
|------------|-------------------------------|--|
| TGL2207-SM | 2.0-6.5 GHz 100W VPIN Limiter | |



Absolute Maximum Ratings

| Parameter | Rating |
|---|---------------|
| Incident Power, CW or Pulsed, 50 Ω , 25 °C | 100 W |
| Incident Power, CW or Pulsed, 50 Ω , 85 °C | 70 W |
| Mounting Temperature (30 s max) | 260 °C |
| Storage Temperature | -40 to 150 °C |

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to device may reduce device reliability.

Recommended Operating Conditions

| Parameter | Min | Тур | Max | Units |
|-------------------|-----|-----|-----|-------|
| Passive – No Bias | | | | |
| Temperature Range | -40 | +25 | +85 | °C |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

Test conditions unless otherwise noted: 25 °C, Tuned EVB Results

| Parameter | Min | Typical | Max | Units |
|--|-----|---------|-----|--------|
| Operational Frequency Range | 2.0 | | 6.5 | GHz |
| Insertion Loss | | < 1.0 | | dB |
| Input Return Loss | | 15 | | dB |
| Output Return Loss | | 15 | | dB |
| Flat Leakage Power at P _{IN} > 30 dBm | | < 15.5 | | dBm |
| Pulse Recovery Time | | < 115 | | ns |
| Spike Leakage | | < 16.0 | | dBm |
| Insertion Loss Temperature Coefficient | | 0.003 | | dB/ °C |

Thermal and Reliability Information

| Parameter | Test Conditions | Value | Units |
|--|--|-------|-------|
| Incident Power (168 Hours RF Operational Life Test ⁽¹⁾) | Frequency = 4.5 GHz, CW, 50 Ω , 25 °C | 31 | W |
| | Frequency = 4.5 GHz, Pulsed, PW=10 us, DC=10%, 50 Ω , 25 °C | 100 | W |

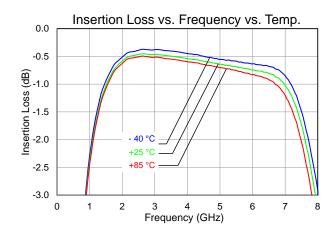
Notes:

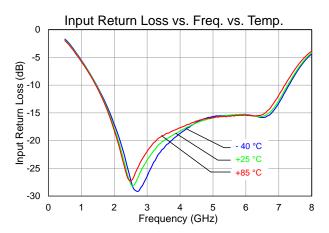
^{1.} Test terminated after 165 hours. Insertion Loss remained ≤ 1 dB for device under test.

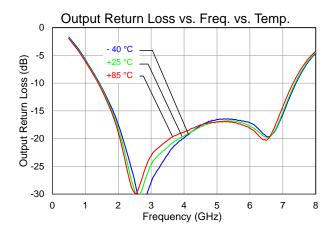


Performance Plots – Small Signal – Tuned EVB Performance

Test conditions unless otherwise noted: Temp.=+25 °C



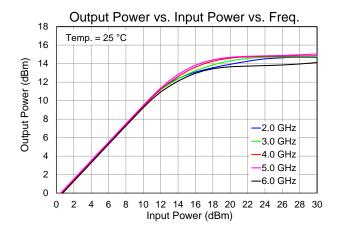


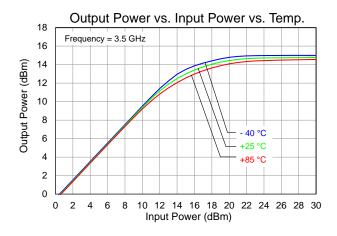


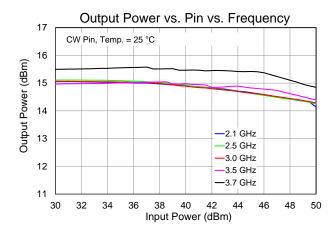


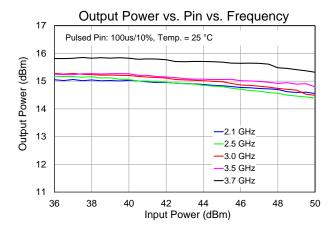
Performance Plots - Large Signal - Tuned EVB Performance

Test conditions unless otherwise noted: CW power, Temp.=+25 °C



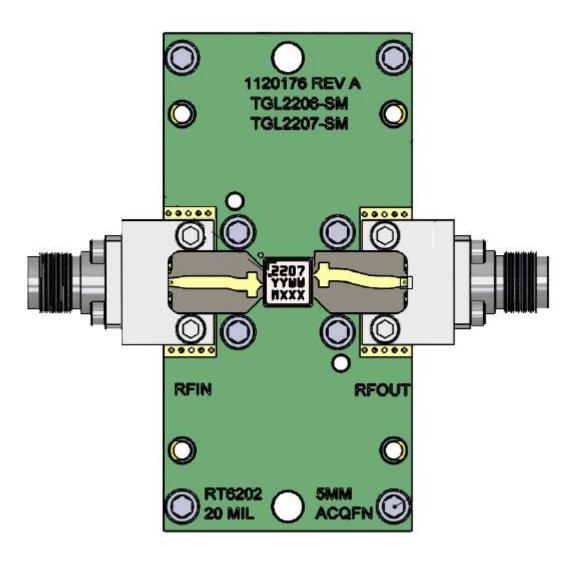








Application Information and Evaluation Board (EVB) Layout



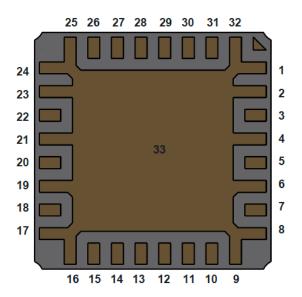
RF layer is 0.020" thick Rogers RO6202, ϵr = 2.94. Metal layers are 1-oz copper. Microstrip 50 Ω line width is 0.050". The microstrip line taper at the connector interface is optimized for the Southwest Microwave end-launch connector 1092-02A-5.

The pad pattern shown has been developed and tested for optimized assembly at Qorvo Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.



Pad Configuration and Description



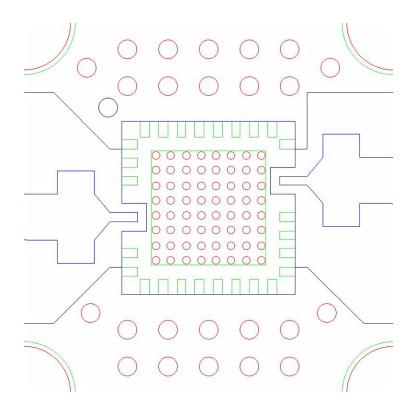


| Pad No. | Label | Description |
|--|-----------|--|
| 1, 2, 4, 6, 8, 9, 16, 17, 19, 21, 23, 24, 25, 32 | | On PCB, multiple vias should be employed under the center pad (33) to minimize inductance and thermal resistance; see page 7 for suggested mounting configuration. |
| 3, 7, 10-15, 18, 20, 26-31 | NC | No connection; may be grounded if desired |
| 5 | RF Input | RF Input, matched to 50 Ohms, not DC blocked |
| 22 | RF Output | RF Output, matched to 50 Ohms, DC blocked |

NOTE: The RF Input and RF Output ports are not interchangeable.



Evaluation Board PCB Mounting Detail

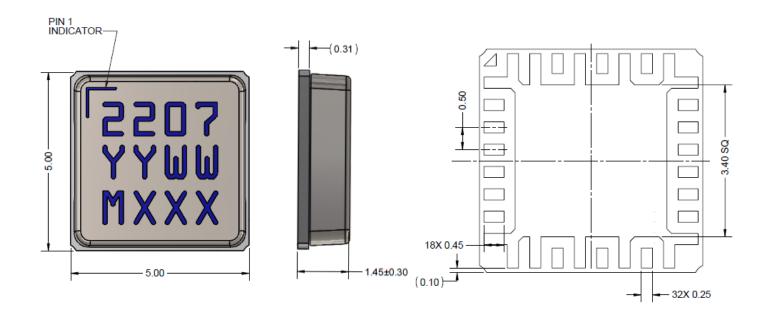


Notes:

- 1. Ground / thermal vias under the DUT are critical for the proper performance of this device.
- 2. The EVB shown herein utilizes copper filled vias (8 mil diameter) under the DUT to maximize heat transfer away from the DUT under large signal conditions.
- 3. Thermal dissipation is low for normal non-limiting operation.



Package Marking and Dimensions



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCE IS \pm 0.25

NOTES:

- 1. PACKAGE BASE: CERAMIC
- 2. PACKAGE LID: PLASTIC
- 3. ALL METALIZED FEATURES ARE GOLD PLATED
- 4. THE PART IS EPOXY SEALED
- 5. PART MARKING:

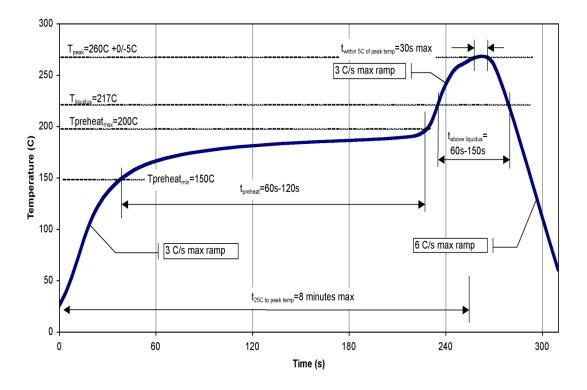
2207: PART NUMBER
YY: PART ASSY YEAR
WW: PART ASSY WEEK
MXXX: BATCH ID



Solderability

- 1. Compatible with the latest version of J-STD-020, Lead-free solder, 260° C.
- 2. The use of no-clean solder to avoid washing after soldering is recommended.
- The package base is ceramic and the plating material on the leads is gold over nickel (Au-Ni).

Recommended Soldering Profile





Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|--------|--------------------------|
| ESD-Human Body Model (HBM) | TBD | ESDA / JEDEC JS-001-2012 |
| ESD - Charged Device Model (CDM) | TBD | JEDEC JESD22-C101F |
| MSL – Moisture Sensitivity Level | TBD | IPC/JEDEC J-STD-020 |



Caution! ESD-Sensitive Device

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: <u>www.qorvo.com</u> Tel: 1-844-890-8163

Email: customer.support@gorvo.com

For technical questions and application information: Email: appsupport@gorvo.com

Important Notice

The information contained herein is believed to be reliable; however, Qorvo makes no warranties regarding the information contained herein and assumes no responsibility or liability whatsoever for the use of the information contained herein. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for Qorvo products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information. THIS INFORMATION DOES NOT CONSTITUTE A WARRANTY WITH RESPECT TO THE PRODUCTS DESCRIBED HEREIN, AND QORVO HEREBY DISCLAIMS ANY AND ALL WARRANTIES WITH RESPECT TO SUCH PRODUCTS WHETHER EXPRESS OR IMPLIED BY LAW, COURSE OF DEALING, COURSE OF PERFORMANCE, USAGE OF TRADE OR OTHERWISE, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE.

Without limiting the generality of the foregoing, Qorvo products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.

Copyright 2019 © Qorvo, Inc. | Qorvo is a registered trademark of Qorvo, Inc.